

## Plastic-Encapsulate Diodes

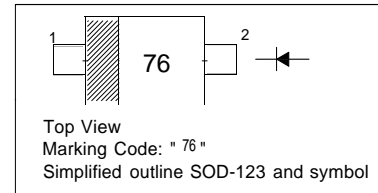
Schottky Barrier Diode

### FEATURES

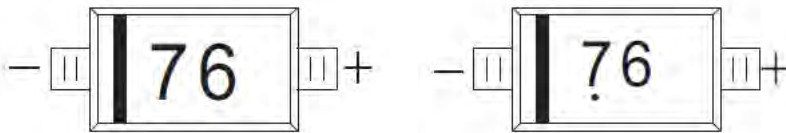
- Small Power Mold Type
- Low  $I_R$
- High Reliability

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



### MARKING: 76



The marking bar indicates the cathode  
Solid dot = Green molding compound device, if none, the normal device.

### Maximum Ratings @ $T_a=25^\circ\text{C}$

Parameter	Symbol	Limit	Unit
DC reverse voltage	$V_R$	60	V
Mean rectifying current	$I_o$	1	A
Peak forward surge current 4 H1, " a g	$I_{FSM}$	F1	A
Power dissipation	$D_8$	350	mW
Thermal Resistance Junction to Ambient	$\theta_{j-a}$	286	$^\circ\text{C}/\text{W}$
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55~+150	$^\circ\text{C}$

### Electrical characteristics @ $T_a=25^\circ\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	$V_F$			0.58	V	$I_F=1\text{A}$
Reverse current	$I_R$			30	$\mu\text{A}$	$V_R=60\text{V}$



**CHINA BASE**  
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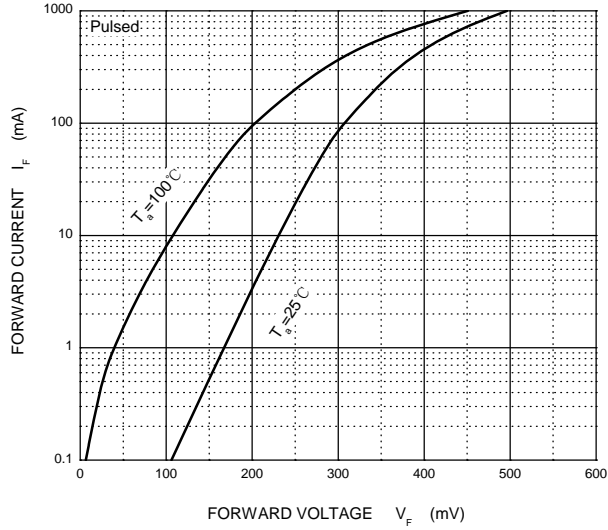
**SOD-123**



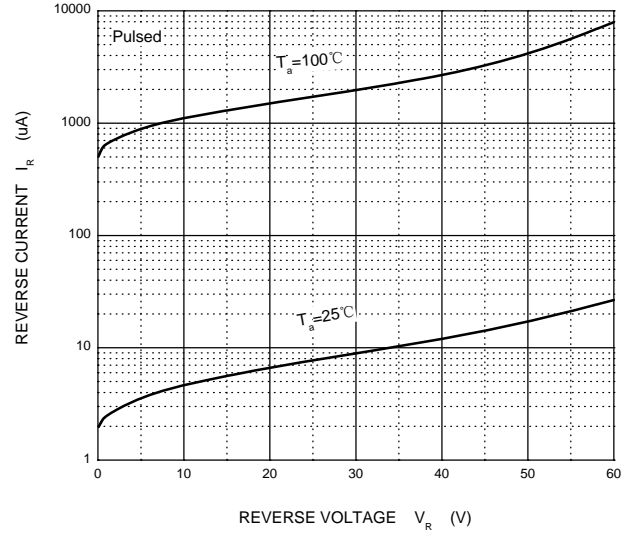
**RB160M-60**

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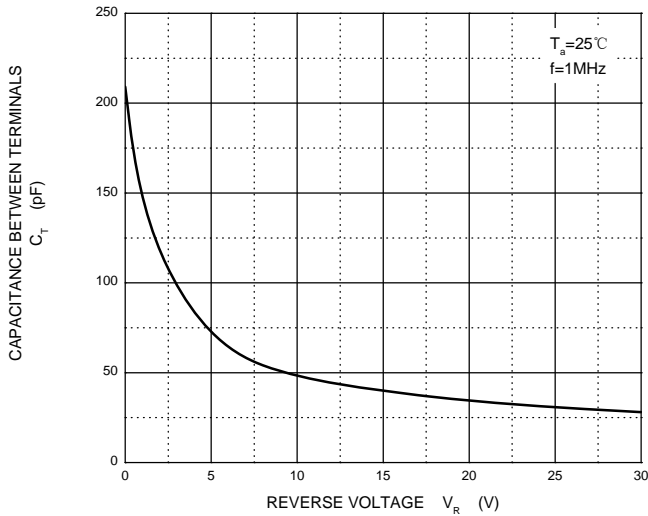
**Forward Characteristics**



**Reverse Characteristics**



**Capacitance Characteristics**



**Power Derating Curve**

